

EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



Technical Informations

Voltage:	35Volt
Range;	1,0µF
Dimension; D x L mm	4x5,4mm
Impedance (Ω) max., at20°C, 100hKz	3,0Ω
Ripple Current (mA rms) at 105°C, 100kHz	60mA

Ordering Code			
350	Voltage		
1R0	Range		
D=	A	L=	0

Low Impedance with Operating Temperatur Range of -55°C ~ +105°C
Load Life of 1000~2000hours

Leakage current max.	Ø4 ~ Ø10mm	I= 0,01CV or 3µA whichever is greater (after 2 minutes)
	Ø12,5 ~ Ø16mm	I= 0,03CV or 4µA whichever is greater (after 1 minutes)

Capacitance tolerance ± 20% at 120Hz, 20°C

Dissipation factor max. (at 120Hz, 20°C)	WV		6,3	10	16	25	35	50						
	Tanδ	Ø4 ~ Ø10mm	0,22	0,19	0,16	0,14	0,12	0,12						
		Ø12,5 ~ Ø16mm	0,26	0,22	0,18	0,16	0,14	0,12						

Low Temperatur characteristics (Impedance ratio at 120Hz)	WV		6,3	10	16	25	35	50						
	Ø4 ~ Ø10mm	Z-25°C / Z+20°C	2	2	2	2	2	2						
		Z-55°C / Z+20°C	5	4	4	3	3	3						
	Ø12,5 ~ Ø16mm	Z-25°C / Z+20°C	3	3	2	2	2	2						
Z-55°C / Z+20°C		10	8	6	4	3	3							

Load Life (after application of the rated voltage for 2000hrs at 105°C	Leakage current	Less than specified value
	Capacitance Change	Within ±20% of initial value
	Tanδ	Less than 200% of specified value
	Ø4 ~ Ø6,3x5,4: 1000hours	

CHIP Low Impedance 105°C

Part No.: **I15008**

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Shell life (at 105°C) After 1000hours no load test, leakage current, capacitance and tan δ are same as load life value.

Resistance to soldering heat	After reflow soldering and resistance at room temperature, they meet the characteristics requirements listed at underside	
	Leakage current	Less than specified value
	Capacitance Change	Within $\pm 10\%$ of initial value
	Tan δ	Less than specified value

Size	FREQUENCY COEFFICIENT OF PERMISSIBLE RIPPLE CURRENT					
	Capacitance μF	Frequency				
		50Hz	120Hz	300Hz	1KHz	10KHz \leq
$\text{\O}4 \sim \text{\O}10\text{mm}$	1,0~ 68	0,35	0,50	0,64	0,83	1,00
	100~2200	0,40	0,55	0,70	0,85	1,00
$\text{\O}12,5 \sim \text{\O}16\text{mm}$	~680	0,45	0,65	0,80	0,90	1,00
	1000 ~4700	0,65	0,85	0,95	1,00	1,00

CHIP Low Impedance 105°C	
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Technical Drawing

Dimension of Size \varnothing 8x10,5 ~ 16mm



Dimension of Size \varnothing 4~ 8x6,2mm



D x L	\varnothing 4 x 5,4	\varnothing 5 x 5,4	\varnothing 6,3 x 5,4	\varnothing 6,3 x 7,7	\varnothing 8 x 6,2	\varnothing 8 x 10,5	\varnothing 10 x 10,5	\varnothing 10 x 13,5	\varnothing 12,5 x 13,5	\varnothing 12,5 x 16	\varnothing 16 x 16,5
A	2,0	2,2	2,6	2,6	3,4	3,0	3,3	3,3	4,9	4,9	5,8
B	4,3	5,3	6,6	6,6	8,4	8,4	10,4	10,4	13,0	13,0	17,0
C	4,3	5,3	6,6	6,6	8,4	8,4	10,4	10,4	13,0	13,0	17,0
E +/-0.2	1,0	1,3	1,9	1,9	2,3	3,1	4,7	4,7	4,7	4,7	6,4
L	5,4	5,4	5,4	7,7	6,2	10,5	10,5	13,5	13,5	16,0	16,5

*1 Voltage mark (6V) represents 6,3V for \varnothing 4 ~ 10mm

*3 (L +/- 0.5) is applicable to \varnothing 8x10,5 ~ \varnothing 10mm

*2 (L +/- 0.3) is applicable to \varnothing 6,3 ~ 7.7 and \varnothing 8 + 6,2mm

*4 (L +/- 1.0) is applicable to \varnothing 12,5 ~ \varnothing 16mm

RE. Date code and seriew type -1st digit for Year 2nd digit for Quarter, 4 quarter codes in one year area 1,4,7,0

3rd character for Serie S

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Ordering Informations

Serie	Voltage Code	Tolerance Code	Range Code	Size Code D	Size Code L	Special function	ROHS	Packing Code		
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I15008	350	M	1R0	A	0	XX	R	TR		
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look table	M= ±20%	Ordering Code Range	Look table Code D	Look table Code L	XX= No function	R= ROHS Conform	TR= Tape Reel Packing		
Voltage Code						N= NON ROHS Conform			
							BU= Bulk-Ware		

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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



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